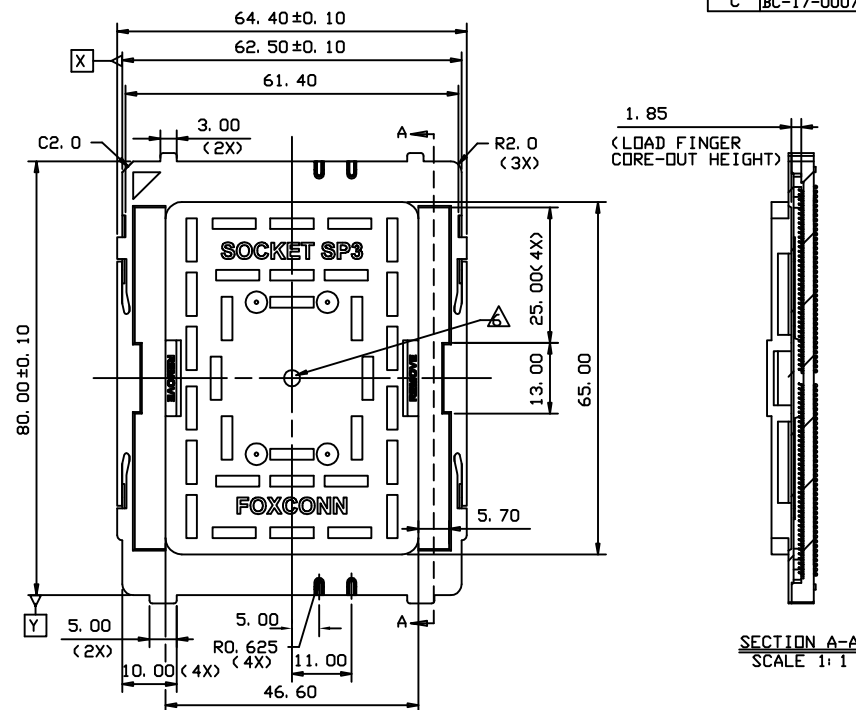
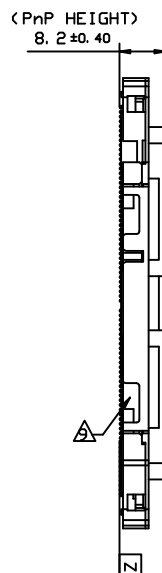
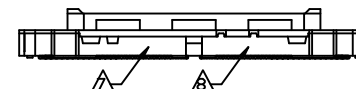


REV.	ECN. NO.	APPD.
A	BC-15-0057549	S. SZU
B	BC-16-0045917	S. SZU
C	BC-17-0007072	Nick Lin



1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
3. MATERIAL : SOCKET HOUSING LCP, BLACK,UL94V-0;
CONTACT C7035-TM06, THICKNESS 0.08±0.005mm;
CONTACT PLATING 30u"Au MIN. OVER 50u"Ni MIN. OVERALL
SOLDER BALL SnAgCu;
PICKUP CAP LCP, BLACK,UL94V-0;
4. THICKNESS OF SOCKET (FROM SEATING PLANE TO PCB): 2.70±0.20 AFTER SOLDERING PROCESS
5. PACKAGE SEATING PLANE FLATNESS : 0.25mm MAX.
CONTACT TIP COPLANARITY : 0.20mm MAX.
CONTACT TIP FEATURE AND PATTERN T.P. : 0.25mm MAX.
CONTACT LOCAL HEIGHT: 0.55±0.10mm
- △ SOCKET CENTER OF GRAVITY MARK POSITION;
- △ FOXCONN LOGO IS LOCATED APPROXIMATELY HERE;
- △ SOCKET NAME IS LOCATED APPROXIMATELY HERE;
- △ DATE CODE IS LOCATED APPROXIMATELY HERE;
- △ CORECUT DEPTH MIGHT HAVE VARIATION POINT BY POINT.
11. THE CONCENTRATIONS OF Br & Cl CAN SATISFY THE REQUIREMENTS OF HALOGEN-FREE IN DOCUMENT EP112.
12. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.



X. ±	X. ° ± 1°	UNITS mm	NAME (INTENDED USE)	FOXCONN®								
. X ± 0. 20	. X ° ±	MAT'L △	SOCKET SP3	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.								
. XX ± 0. 10	. XX ° ±	FINISH	PART NO. (INTENDED USE)	CLASS: ☐ CONFIDENTIAL ☐ SECRET ☒ GENERAL								
. XXX ±	. XXX ° ±		PE40943-81ANO-1H	TITLE: CUSTOMER DRAWING FOR SOCKET SP3								
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: Nick Lin	DWG NO.: 351-0000-1375								
		CHKD: Dickie Huang Mac Peng	<table><tr><td>SCALE</td><td>SHEET</td><td>REV.</td></tr><tr><td>1: 1</td><td>1/4</td><td>C</td></tr></table>				SCALE	SHEET	REV.	1: 1	1/4	C
		SCALE					SHEET	REV.				
1: 1	1/4	C										
		Q' TY	DR: Alex Ai 03/16/17									

FOXCONN CONFIDENTIAL

FK2B00065A